

Electronic Patent Application Fee Transmittal

Application Number:	10537416			
Filing Date:	02-Jun-2005			
Title of Invention:	CONNECTION STRUCTURE FOR COAXIAL CONNECTOR AND MULTILAYER SUBSTRATE			
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Attorney Docket Number:	273258US2PCT			
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Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
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Patent-Appeals-and-Interference:				
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